



## Material Content Data Sheet



<b>Sales Product Name</b>		BC 847S H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001094634						
<b>Package</b>		PG-SOT363-6-1		<b>Weight*</b>		6.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.006	0.09		935	
	non noble metal	arsenic	7440-38-2	0.000	0.00		9	
	inorganic material	silicon	7440-21-3	0.050	0.80	0.89	7988	8932
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1378	
	non noble metal	copper	7440-50-8	2.869	45.74	45.94	457409	459338
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1635	1635
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4871	
	plastics	epoxy resin	-	0.657	10.47		104735	
	inorganic material	silicondioxide	60676-86-0	2.368	37.75	48.71	377533	487139
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	33994	33994
plating	noble metal	silver	7440-22-4	0.056	0.90	0.90	8962	8962
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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